VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION:

Specification at page 7, line 3:

~~A 1st invention~~One aspect of the present invention ~~(corresponding to claim 1)~~ is a transducer-supporting structure, characterized in that said structure at least comprises:

Specification at page 7, line 23:

~~A 2nd invention~~Another aspect of the present ~~invention (corresponding to claim 2)~~ is the transducer-supporting structure ~~according to the first invention~~, characterized in that said thermal coupling member has an elastic restoring force, and is in contact with said transducer.

Specification at page 8, line 3:

~~A 3rd invention~~ Still another aspect of the present invention ~~(corresponding to claim 3)~~ is the transducer-supporting structure ~~according to the 1st invention~~, characterized in that said transducer is an electromagnetic transducer.

Specification at page 8, line 7:

~~A 4th invention~~ Yet still another aspect of the present invention ~~(corresponding to claim 4)~~ is the transducer-supporting ~~structure according to the 1st invention~~, characterized in that said transducer is an electro-optical transducer.

Specification at page 8, line 11:

~~A 5th invention~~ Still yet another aspect of the present invention ~~(corresponding to claim 5)~~ is a transducer-supporting structure, characterized in that said structure at least comprises:

Specification at page 9, line 9:

~~A 6th invention~~ A further aspect of the present ~~invention (corresponding to claim 6)~~ is a transducer-supporting structure, characterized in that said structure at least comprises:

Specification at page 10, line 7:

~~A 7th invention~~ A still further aspect of the present invention ~~(corresponding to claim 7)~~ is a transducer-supporting structure, characterized by at least comprising:

Specification at page 10, line 16:

~~An 8th invention~~A yet further aspect of the present invention ~~(corresponding to claim 8)~~ is the transducer-supporting ~~structure according to the 7th invention~~, characterized in that said transducer is an electromagnetic transducer.

Specification at page 11, line 1:

~~A 9th invention~~ A still yet further aspect of the present invention ~~(corresponding to claim 9)~~ is the transducer-supporting structure ~~according to the 7th invention~~, characterized in that said transducer is an electro-optical transducer

Specification at page 18, line 3:

Reference numeral 15 denotes a viscous liquid material with relatively high thermal conductivity, such as a gel-form heat conductive material. For example, silicone grease is preferably selected as the heat conductive material 15. The heat conductive material 15 is stuck in the vicinity of a contact region of the thermally coupling contact portion 13d and the magnetic core ~~4~~2.

Specification at page 19, line 17:

FIG. 7 shows an essential part of a transducer-supporting structure in accordance with a ~~second~~ third embodiment of the present invention. A slider 1, a magnetic core 2, a coil 4, and a disk 10 are the same as those elements of the first

embodiment. Although the whole of a suspension is not shown in FIG. 7, the suspension is approximately the same as the suspension 3 of the first embodiment, and a gimbal portion 23b is the same as the gimbal portion 3b of the first embodiment.

Specification at page 20, line 1:

A tongue 23c is approximately the same as the tongue 103c of the conventional example, and is connected to the slider 1. However, the tongue 23c differs from the tongue 103c in that it extends longer toward the magnetic core 2 than the tongue 103c. Reference numeral 25 denotes a gel-form heat conductive material with relatively high thermal conductivity. In this embodiment, the heat conductive material 25 functions as a thermal coupling member, and is applied to the magnetic core 42, the tongue 23c, and a gap there between.

Specification at page 22, line 6:

The following will be a description of the operation of the transducer-supporting structure constructed as described above.

Specification at page 23, line 3:

The semiconductor laser 8a generates a large amount of heat relative to the volume thereof. However, since the suspension 33 is connected to the semiconductor laser 8a, the heat can be dissipated through the suspension 33, so that a rise in temperature of the semiconductor laser 8a can be neglected. For this reason, the life of the semiconductor laser 8a increases. Also, a rise in temperature of the whole of the integrated optical system 8 can be prevented. Therefore, even in the case where an element whose shape is wavelength dependent such as a hologram element is used, the influence of thermal expansion can be neglected, so that the reliability and hostile-environment resistance are improved. Also, a hologram element formed of a resin sensitive to thermal expansion can be used, which achieves a reduction in cost.

Specification at page 24, line 7:

A magnetic core 42 has the whole shape that is approximately the same as that of the magnetic core 4~~-~~2 of the first embodiment, but differs from the magnetic core 4 in that the magnetic core 42 has a heat dissipating portion 42b as heat dissipating means.